

Electronic Acknowledgement Receipt

EFS ID:	1308293
Application Number:	10710826
International Application Number:	
Confirmation Number:	4825
Title of Invention:	METHOD OF FORMING STRAINED SILICON MATERIALS WITH IMPROVED THERMAL CONDUCTIVITY
First Named Inventor/Applicant Name:	Stephen W. Bedell
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Filer Authorized By:	Yuanmin Cai
Attorney Docket Number:	FIS920040069
Receipt Date:	13-NOV-2006
Filing Date:	05-AUG-2004
Time Stamp:	13:37:45
Application Type:	Utility

Payment information:

Submitted with Payment	no
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part/.zip	Pages (if appl.)
1	Amendment After Final	FIS920040069RESPONSE.pdf	109453	no	5

Warnings:

Information:	Total Files Size (in bytes):	109453
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